120V N-Ch Power MOSFET

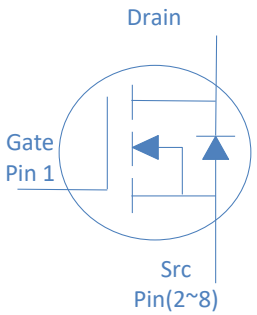
Feature

- ◇ High Speed Power Smooth Switching
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free

V_{DS}	120	V
$R_{DS(on),TYP}$	3.3	mΩ
$I_{D\ (Sillicon\ Limited)}$	203	A

Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ Power Tools
- ◇ UPS
- ◇ Motor Control



Part Number	Package	Marking
HGT035N12S	TOLL	GT035N12S

Absolute Maximum Ratings at T_j=25℃ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	T_C=25℃	203	A
		T_C=100℃	143	
Drain to Source Voltage	V_{DS}	-	120	V
Gate to Source Voltage	V_{GS}	-	±20	V
Pulsed Drain Current	I_{DM}	-	550	A
Avalanche Energy, Single Pulse	E_{AS}	L=0.1mH, T_C=25℃	180	mJ
Power Dissipation	P_D	T_C=25℃	357	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to175	℃

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\Theta JC}$	0.42	℃/W
Thermal Resistance Junction-Ambient	$R_{\Theta JA}$	60	℃/W

Electrical Characteristics at T_j=25℃ (unless otherwise specified)

Static Characteristics

Parameter	Symbol	Conditions		Value			Unit
				min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250μA		120	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS}=V_{DS}, I_D=250μA		2	3	4	
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS}=0V, V_{DS}=120V, T_j=25℃		-	-	1	μA
		V_{GS}=0V, V_{DS}=120V, T_j=100℃		-	-	100	
Gate to Source Leakage Current	I_{GSS}	V_{GS}=±20V, V_{DS}=0V		-	-	±100	nA
Drain to Source on Resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=20A	TOLL	-	3.3	3.9	mΩ
Transconductance	g_{fs}	V_{DS}=5V, I_D=20A		-	70	-	S
Gate Resistance	R_G	V_{GS}=0V, V_{DS} Open, f=1MHz		-	2.9	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	V_{GS}=0V, V_{DS}=60V, f=1MHz	-	6427	-	pF
Output Capacitance	C_{oss}		-	716	-	
Reverse Transfer Capacitance	C_{rss}		-	10	-	
Total Gate Charge	Q_g	V_{DD}=60V, I_D=20A, V_{GS}=10V	-	68	-	nC
Gate to Source Charge	Q_{gs}		-	20	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	8	-	
Turn on Delay Time	$t_{d(on)}$	V_{DD}=60V, I_D=20A, V_{GS}=10V, R_G=10Ω,	-	27	-	ns
Rise time	t_r		-	20	-	
Turn off Delay Time	$t_{d(off)}$		-	39	-	
Fall Time	t_f		-	12	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_F=20A	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	V_R=60V, I_F=20A, dI_F/dt=500A/μs	-	60	-	ns
Reverse Recovery Charge	Q_{rr}		-	420	-	nC

Fig 1. Typical Output Characteristics

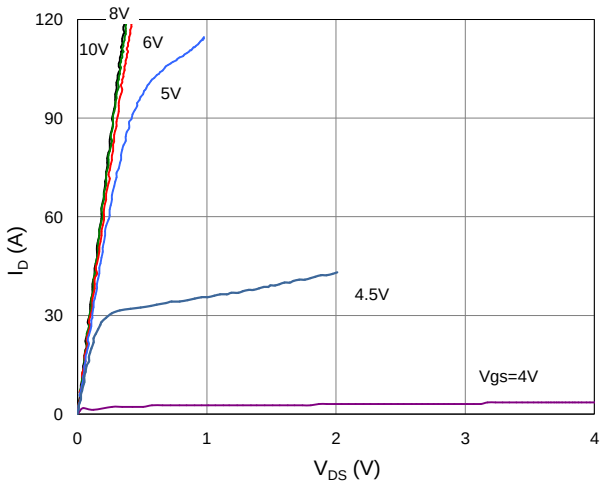


Figure 2. On-Resistance vs. Gate-Source Voltage

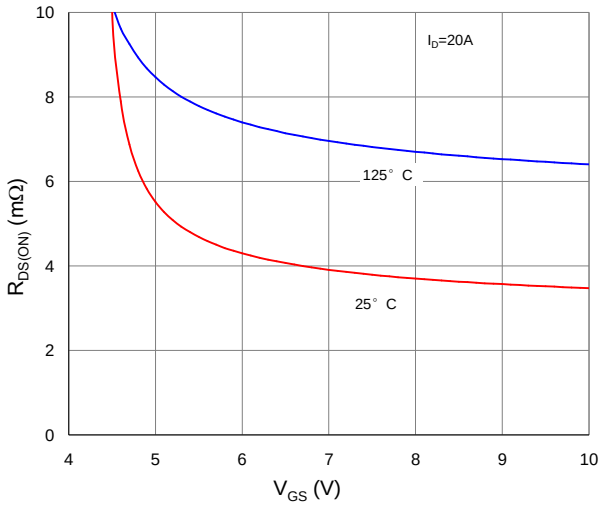


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

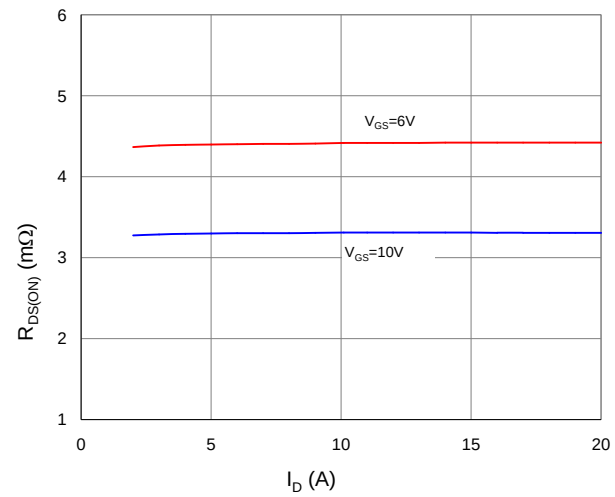


Figure 4. Normalized On-Resistance vs. Junction Temperature

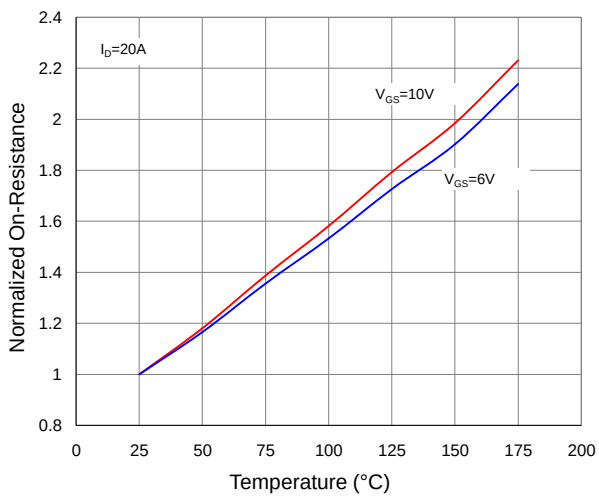


Figure 5. Typical Transfer Characteristics

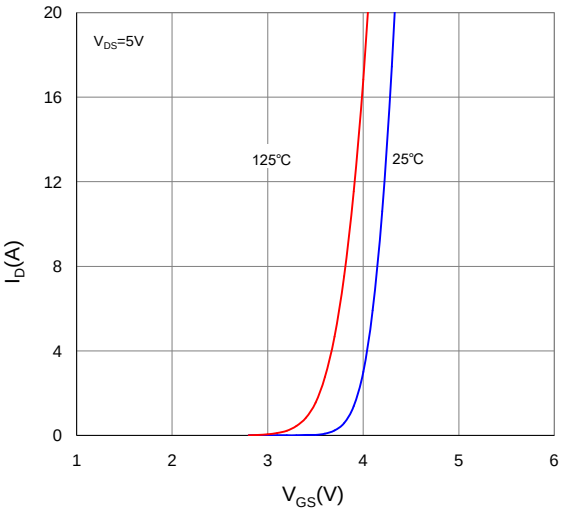


Figure 6. Typical Source-Drain Diode Forward Voltage

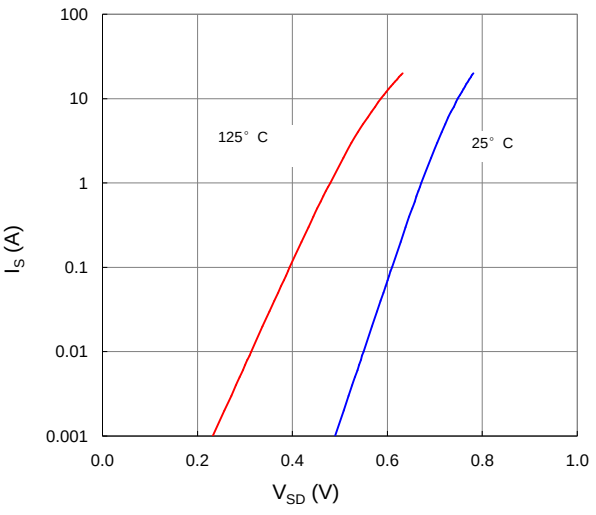


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

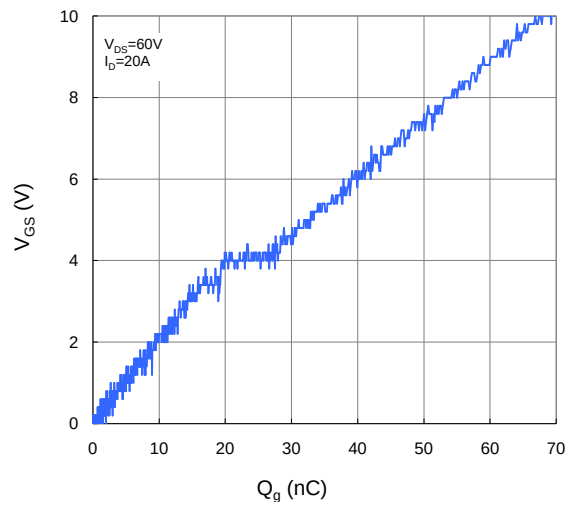


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

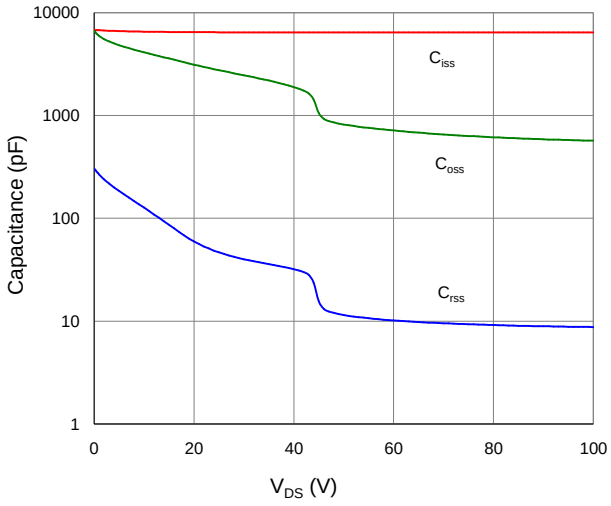


Figure 9. Maximum Safe Operating Area

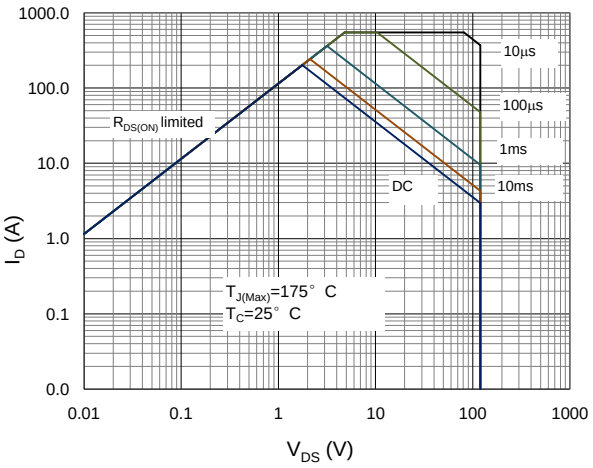


Figure 10. Maximun Drain Current vs. Case Temperature

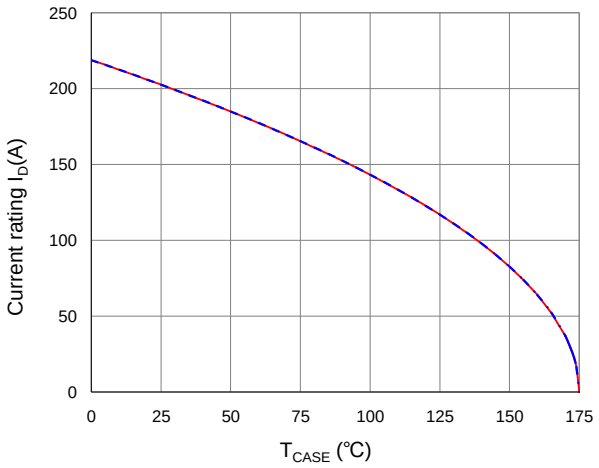
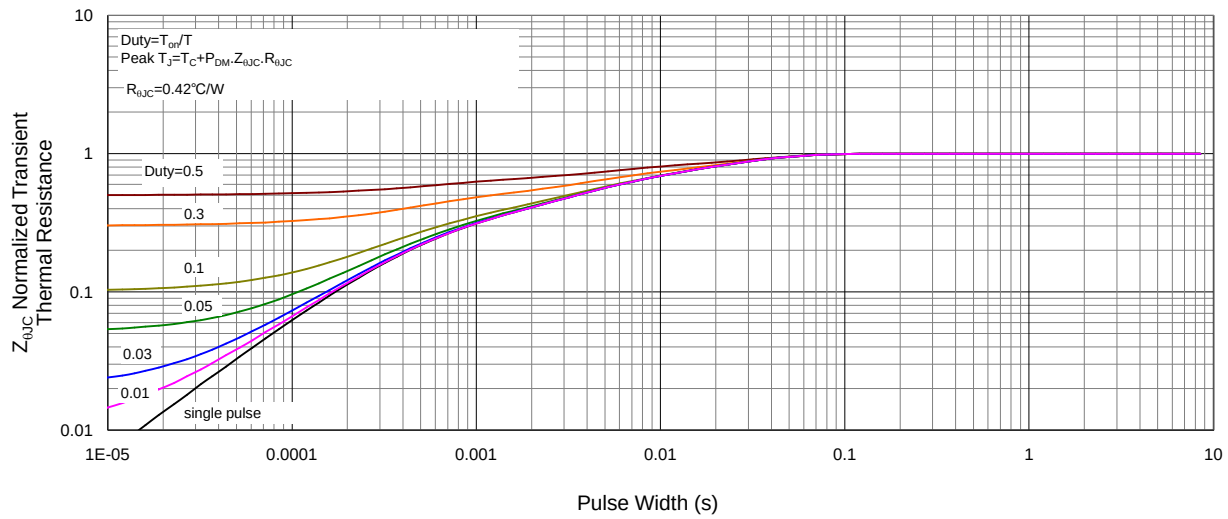
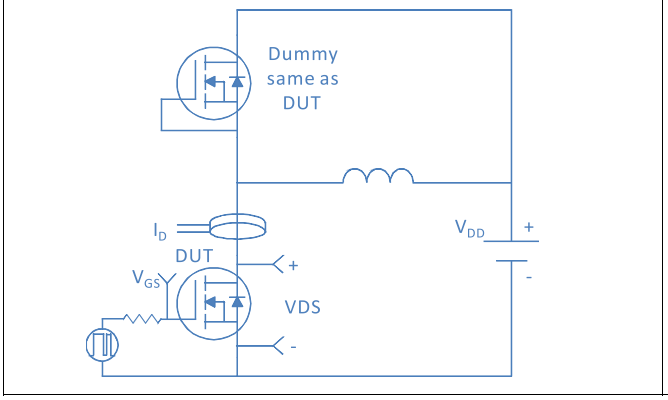
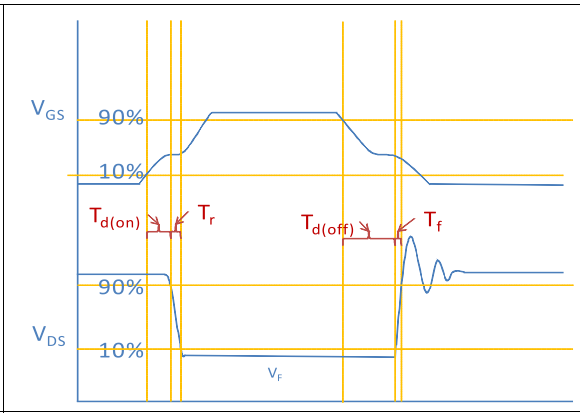


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case

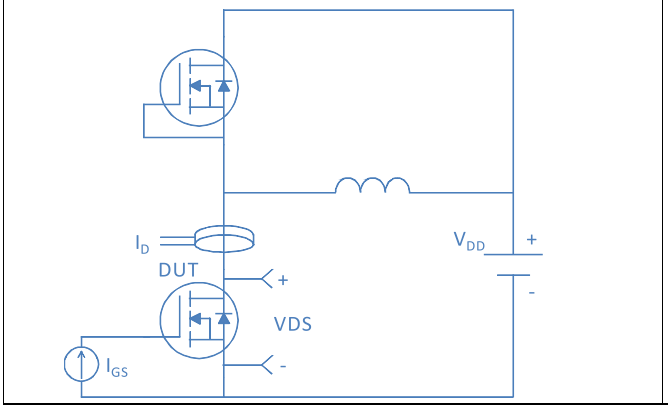


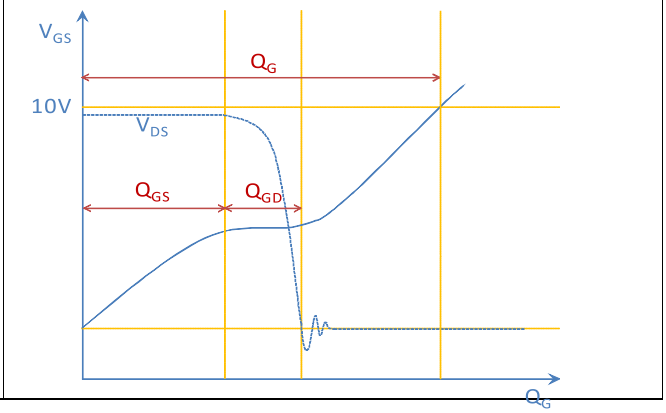
Inductive switching Test



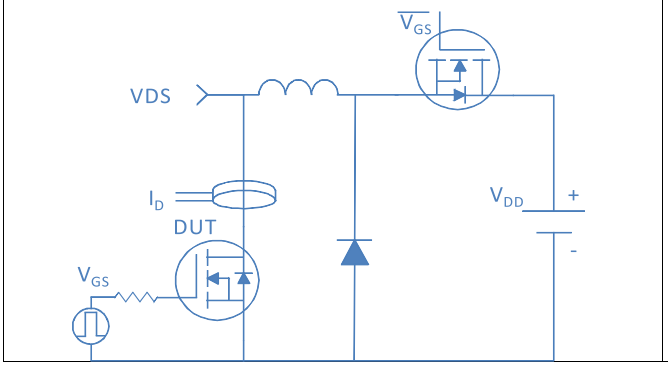


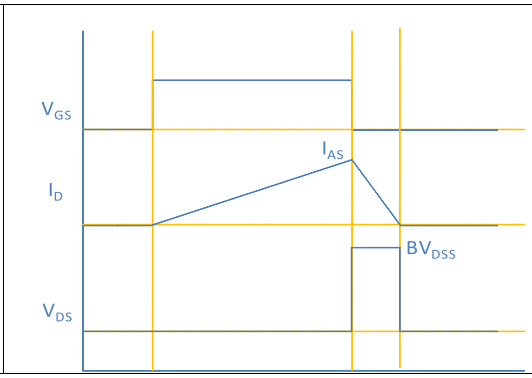
Gate Charge Test



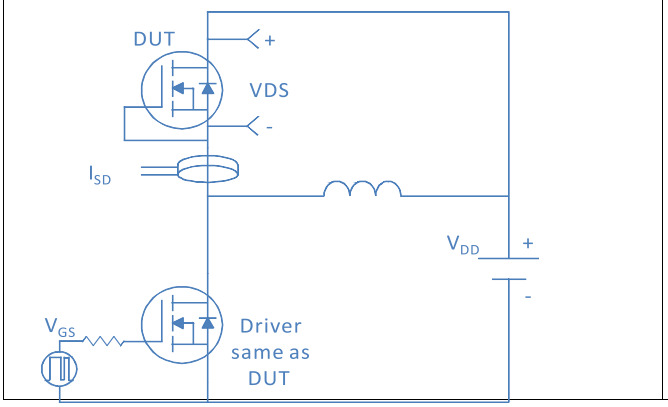


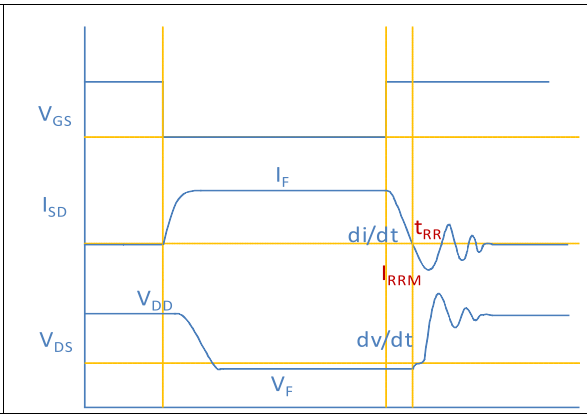
Uclamped Inductive Switching (UIS) Test



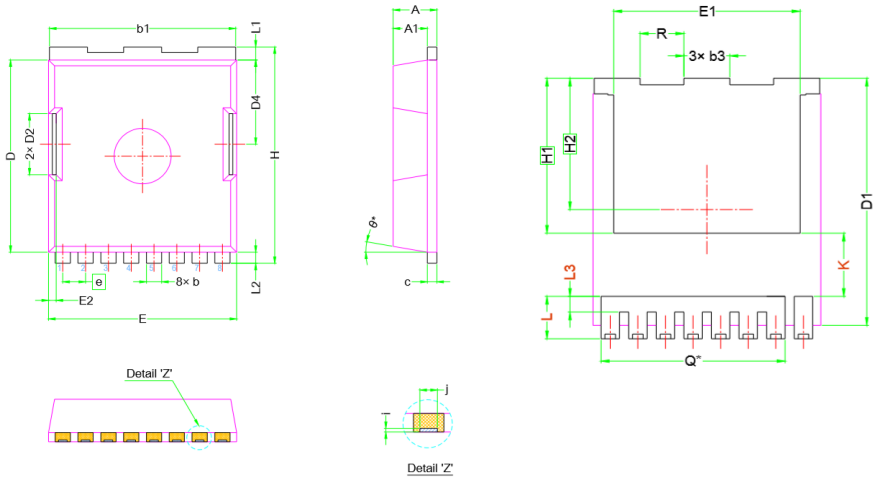


Diode Recovery Test





TOLL,8 leads



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
A1	1.70	1.80	1.90
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b3	1.90	2.00	2.10
c	0.40	0.50	0.60
D	10.28	10.38	10.48
D1	10.98	11.08	11.18
D2	3.20	3.30	3.40
D4	4.45	4.55	4.65
E	9.80	9.90	10.00
E1	8.00	8.10	8.20
E2	0.30	0.40	0.50
e	1.20 BSC		
H	11.58	11.68	11.78
H1	6.95 BSC		
H2	5.89 BSC		
i	0.10 REF.		
j	0.46 REF.		
K	2.80 REF.		
L	1.60	1.90	2.10
L1	0.60	0.70	0.80
L2	0.50	0.60	0.70
L3	0.60	0.70	0.80
N	8		
Q	6.80 REF.		
R	1.80	1.90	2.00
θ	10° REF.		